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(43) **Pub. Date: Nov. 24, 2022**(54) **PRINTED CIRCUIT BOARD AND FLUID HEATER**(71) Applicant: **DBK David + Baader GmbH**,  
Rülzheim (DE)(72) Inventors: **Sebastian SCHÖNEICH**, Rülzheim  
(DE); **Alexander KRÄMER**,  
Kapsweyer (DE); **Simon FISCHER**,  
Karlsruhe (DE)(73) Assignee: **DBK David + Baader GmbH**,  
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(2013.01)(57) **ABSTRACT**

A printed circuit board includes a conducting path shaped via a subtractive method and a heating line. The heating line is formed by the conducting path and designed to have a predetermined heating power for a heating fluid. The printed circuit board further includes a heat dispersion layer designed for transferring heat to the fluid. A heater includes such a printed circuit board.

